

# 1 MOS Model, level 40

# 1.1 Introduction

The Silicon On Isolator (SOI) Field-Effect Transistor (FET) is a semiconductor device whose operation is achieved by modulation of the resistance of a thin silicon layer (channel). The modulation of the resistance is controlled by the gate voltage and handle wafer (box) voltage. These devices are often used as a load in high voltage MOS devices. This long channel SOI FET model is special developed to describe the drift region of LDMOS and EPMOS devices. When the n-channel FET transistor equations are used for p-channel FET transistors, the sign of the terminal potentials, terminal currents and terminal charges must be changed.

## 1.1.1 Survey of modeled effects

- Accumulation/depletion at the surface
- Accumulation/depletion at the box
- Pinch off mode
- Velocity saturation in the channel
- Gate charge model
- Self-heating
- Box charge model
- Different temperature scaling for *RON* and *VSAT*
- Include temperature scaling for *RSAT*.

Not included in the model

- Short channel effects
- Subthreshold currents
- Inversion at the surface at high negative gate voltages
- Inversion at the box at high negative box voltages
- Noise model.



## 1.2 Parameters and constants

### 1.2.1 Parameters and clipping

#### Parameter list

The parameters are listed below.

Parameter	Units	Description
<i>LEVEL</i>	-	Model level, must be set to 40
<i>PARAMCHK</i>	-	Level of clip warning info *)
<i>RON</i>	$\Omega$	Ohmic resistance at zero bias
<i>RSAT</i>	$\Omega$	Space charge resistance at zero bias
<i>VSAT</i>	V	Critical drain-source voltage for hot carriers
<i>PSAT</i>	-	Velocity saturation coefficient
<i>VP</i>	V	Pinch off voltage at zero gate and handle wafer voltages $VP \leq 0$ no depletion and/or accumulation in the channel
<i>TOX</i>	m	Gate oxide thickness $TOX > 0$ SOI FET device $TOX \leq 0$ No depletion/accumulation at the gate
<i>DCH</i>	$m^{-3}$	Doping level channel
<i>TBOX</i>	m	Box oxide thickness $TBOX \leq 0$ No depletion/accumulation at the box
<i>CGATE</i>	F	Gate capacitance at zero bias
<i>CBOX</i>	F	Handle wafer capacitance at zero bias
<i>TAUSC</i>	s	Space charge transit time of the channel
<i>ACH</i>	-	Temperature coefficient resistivity of the channel
<i>ACHMOD</i>	-	Parameter to switch to extended temperature scaling
<i>ACHRON</i>	-	Temperature coefficient of ohmic resistance at zero bias
<i>ACHVSAT</i>	-	Temperature coefficient of critical drain-source voltage for hot carriers
<i>ACHRSAT</i>	-	Temperature coefficient of space charge resistance at zero bias
<i>TREF</i>	$^{\circ}C$	Reference temperature

Parameter	Units	Description
<i>DTA</i>	°C	Temperature offset to the ambient temperature
<i>MULT</i>	–	Multiplication factor
<i>PRINT-SCALED</i>	–	Flag to add scaled parameters to the OP output

\*) See Appendix D for the definition of PARAMCHK.

The additional parameters for the model including self-heating are listed below.

Parameter	Units	Description
<i>RTH</i>	°C/W	Thermal resistance
<i>CTH</i>	J/°C	Thermal capacitance
<i>ATH</i>	–	Thermal coefficient of the thermal resistance

### Parameter *MULT*

This parameter may be used to put several devices in parallel. The following parameters are multiplied by *MULT* :

*CGATE*   *CBOX*   *CTH*

Divided by *MULT* are:

*RON*   *RSAT*   *RTH*

### Default and clipping values

The default values and clipping values as used for the MOS level 40 model are listed below.

Parameter name	Units	Default	Clip low	Clip high
<i>LEVEL</i>	-	40	-	-
<i>PARAMCHK</i>	-	0	-	-
<i>RON</i>	Ω	1.00	1e-2	-
<i>RSAT</i>	Ω	1.00	1e-2	-
<i>VSAT</i>	V	10.00	1.00 × 10 <sup>-6</sup>	-
<i>PSAT</i>	–	1.00	0.1	-

<b>Parameter name</b>	<b>Units</b>	<b>Default</b>	<b>Clip low</b>	<b>Clip high</b>
<i>VP</i>	V	-1.00	-1.0	-
<i>TOX</i>	m	-1.00	-1.0	0.0001
<i>DCH</i>	m <sup>-3</sup>	1.00 × 10 <sup>21</sup>	1.00 × 10 <sup>11</sup>	1.00 × 10 <sup>29</sup>
<i>TBOX</i>	m	-1.00	-1.00	0.0001
<i>CGATE</i>	F	0.00	0.0	-
<i>CBOX</i>	F	0.00	0.0	-
<i>TAUSC</i>	s	0.00	0.0	-
<i>ACH</i>	-	0.00	-	-
<i>ACHMOD</i>	-	0.00	0	1
<i>ACHRON</i>	-	0.00	-	-
<i>ACHVSAT</i>	-	0.00	-	-
<i>ACHRSAT</i>	-	0.00	-	-
<i>TREF</i>	°C	25	-273.0	-
<i>DTA</i>	°C	0.00	-	-
<i>MULT</i>	-	1.00	0.0	-
<i>PRINT-SCALED</i>	-	0	-	-

The default values and clipping values of the additional parameters for the model including self-heating (see section 1.4) are listed below.

<b>Parameter Name</b>	<b>Units</b>	<b>Default</b>	<b>Clip low</b>	<b>Clip high</b>
<i>RTH</i>	°C/W	300.0	0.000	-
<i>CTH</i>	J/°C	3.0 × 10 <sup>-9</sup>	0.000	-
<i>ATH</i>	-	0.0	-	-

## 1.2.2 Model constants

$$q = 1.6021918 \cdot 10^{-19} \text{ C}$$

$$\epsilon_{si} = 1.036 \cdot 10^{-10} \text{C/V} \cdot \text{m}$$

$$\epsilon_{ox} = 3.453 \cdot 10^{-11} \text{C/V} \cdot \text{m}$$

$$\left(\frac{k}{q}\right) = 0.86171 \times 10^{-4} \text{V/K}$$

$$\delta_v = 10^{-8}$$

$$\delta_q = 10^{-2}$$

$$V_0 = 10^{-3}$$

The default reference temperature *TREF* for parameter determination is 25 °C.

## 1.3 Model equations

### 1.3.1 Equivalent circuit and equations

A full description of the long channel SOI FET model is given below.

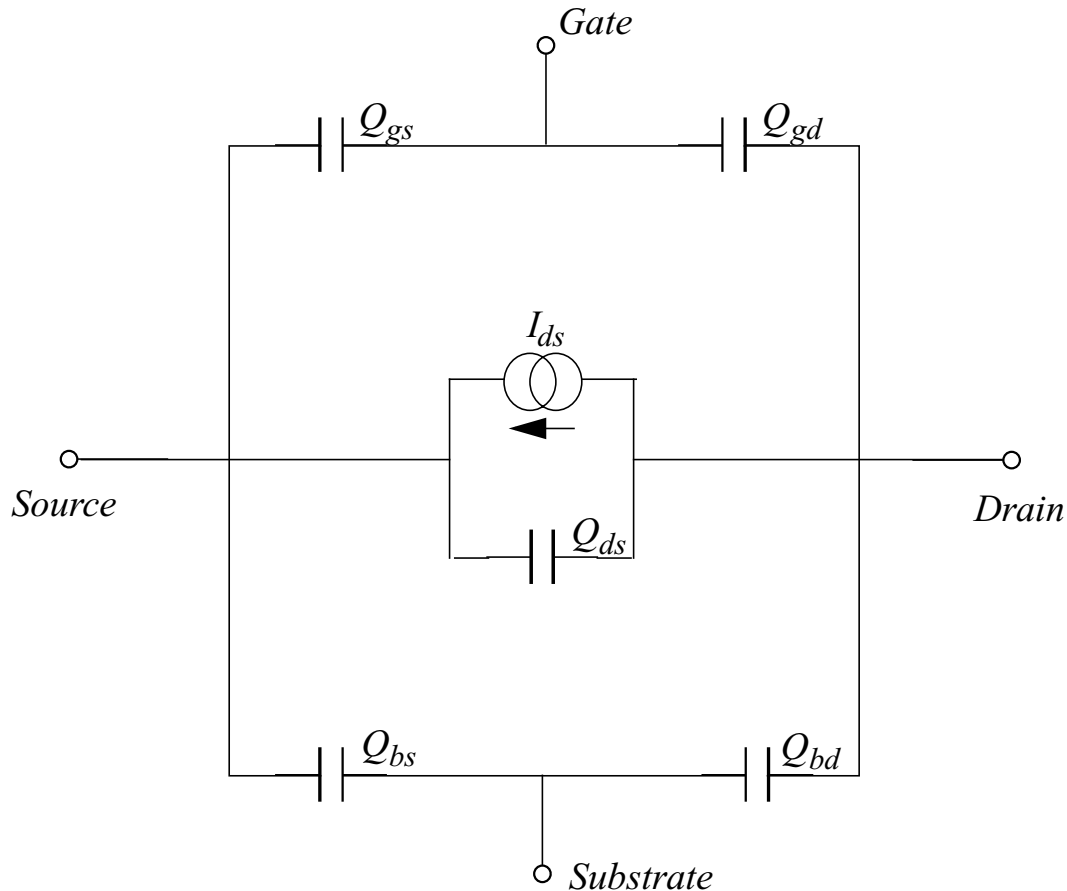


Figure 1: Equivalent Circuit of an SOI FET

### 1.3.2 Temperature effects

The actual simulation temperature is denoted by  $TEMP$  (in  $^{\circ}C$ ). The temperature at which the parameters are determined is  $TREF$  (in  $^{\circ}C$ ).

- Conversions to Kelvins

$$T_K = TEMP + DTA + 273.15 + V_{dT} \quad (1.1)$$

$$T_{amb} = TEMP + DTA + 273.15 \quad (1.2)$$

$$T_{RK} = TREF + 273.15 \quad (1.3)$$

$$T_N = \frac{T_K}{T_{RK}} \quad (1.4)$$

- Thermal Voltage

$$V_T = \left(\frac{k}{q}\right) \cdot T_K \quad (1.5)$$

- On resistance and saturation voltage

$$RON_T = RON \cdot T^{ACHRON} \quad (1.6)$$

$$VSAT_T = VSAT \cdot T^{ACHVSAT} \quad (1.7)$$

$$RSAT_T = RSAT \cdot T^{ACHRSAT} \quad (1.8)$$

- Thermal resistance

$$RTH_T = RTH \cdot \left(\frac{T_{amb}}{T_{RK}}\right)^{ATH} \quad (1.9)$$

### 1.3.3 Model preprocessing

- Parameter dependent constants DC part

$$\text{if } TBOX \leq 0: \quad CBOX = 0$$

$$\text{if } TOX \leq 0: \quad CGATE = 0$$

$$\text{if } TOX \leq 0 \ \& \ TBOX \leq 0: \quad VP = 0$$

For both  $TOX$  and  $TBOX$  less than or equal to zero, the pinch off voltage  $VP = 0$ .

When  $VP \leq 0$  only equations 1.24, 1.41, 1.43, 1.54, 1.55, 1.107 and 1.108 are used. In this case the charges  $Q_b$  and  $Q_g$  are equal zero.

$$TBOX > 0: \quad k_b = \sqrt{2 \cdot \epsilon_{si} \cdot q \cdot DCH} \quad (1.10)$$

$$TBOX \leq 0: \quad k_b = 0$$

$$TOX > 0: \quad k_g = \sqrt{2 \cdot \epsilon_{si} \cdot q \cdot DCH} \quad (1.11)$$

$$TOX \leq 0: \quad k_g = 0$$

$$k_{ox} = \sqrt{2 \cdot \epsilon_{si} \cdot q \cdot DCH} \quad (1.12)$$

$$V_{box} = \frac{\epsilon_{si} \cdot q \cdot DCH}{2} \cdot \left( \frac{TBOX}{\epsilon_{ox}} \right)^2 \quad (1.13)$$

$$V_{ox} = \frac{\epsilon_{si} \cdot q \cdot DCH}{2} \cdot \left( \frac{TOX}{\epsilon_{ox}} \right)^2 \quad (1.14)$$

$$Q_{bp} = \frac{k_b \cdot VP}{\sqrt{VP + V_{box}} + \sqrt{V_{box}}} \quad (1.15)$$

$$Q_{gp} = \frac{k_g \cdot VP}{\sqrt{VP + V_{ox}} + \sqrt{V_{ox}}} \quad (1.16)$$

$$Q_{soi} = Q_{bp} + Q_{gp} \quad (1.17)$$

$$TOX > 0: \quad C_{ox} = \frac{\epsilon_{ox}}{TOX} \quad (1.18)$$

$$TOX \leq 0: \quad C_{ox} = 0$$

$$TBOX > 0: \quad C_{box} = \frac{\epsilon_{ox}}{TBOX} \quad (1.19)$$

$$TBOX \leq 0: \quad C_{box} = 0$$

$$C_{soi} = \frac{\epsilon_{si} \cdot q \cdot DCH}{Q_{soi}} \quad (1.20)$$

$$V_m = (\sqrt{VP + V_{box}} + \sqrt{VP + V_{ox}})^2 \quad (1.21)$$

$$V_{g_{sw}} = \frac{Q_{soi}}{k_{ox}} \cdot \left( \frac{Q_{soi}}{k_{ox}} + 2 \cdot \sqrt{V_{box}} \right) \quad (1.22)$$

$$V_{b_{sw}} = \frac{Q_{soi}}{k_{ox}} \cdot \left( \frac{Q_{soi}}{k_{ox}} + 2 \cdot \sqrt{V_{ox}} \right) \quad (1.23)$$

$$VR_{sat} = VSAT_T \cdot \frac{RSAT_T}{RON_T} \quad (1.24)$$

### 1.3.4 Model evaluation

#### Drain and source voltage

$$V_d \geq V_s: \quad sign = 1$$

$$V_{d_1} = V_d$$

$$V_{s_1} = V_s$$

$$V_d < V_s: \quad sign = -1$$

$$V_{d_1} = V_s$$

$$V_{s_1} = V_d$$

- Pinch-off voltage

$$TBOX \leq 0: \quad V_p = VP + V_g \quad (1.25)$$

$$TOX \leq 0: \quad V_p = VP + V_b \quad (1.26)$$

$$TBOX \leq 0, \quad TOX \leq 0 \quad VP = 0 \quad (1.27)$$

$$TOX > 0 \ \& \ TBOX > 0:$$

- $V_g - V_b > V_{gsw}$ :

$$a_g = \left( \frac{C_{ox}}{2 \cdot C_{box}} \right)^2 \quad (1.28)$$

$$b_g = \left( 1 + \frac{C_{ox}}{C_{box}} + \frac{C_{ox}}{C_{soi}} + a_g \cdot \frac{2 \cdot V_g}{V_{box}} \right) \quad (1.29)$$

$$c_g = \frac{2 \cdot C_{box}}{C_{soi}} + \left( \frac{C_{box}}{C_{soi}} \right)^2 + \left( \frac{C_{ox}}{C_{box}} + \frac{C_{ox}}{C_{soi}} \right) \cdot \frac{V_g}{V_{box}} + \left( \frac{C_{ox}}{2 \cdot C_{box}} \cdot \frac{V_g}{V_{box}} \right)^2 + \frac{V_b}{V_{box}} \quad (1.30)$$

$$V_p = V_{box} \cdot \frac{2 \cdot c_g}{b_g + \sqrt{b_g^2 - 4 \cdot a_g \cdot c_g}} \quad (1.31)$$

- $V_g - V_b < -V_{b_{sw}}$ :

$$a_b = \left( \frac{C_{box}}{2 \cdot C_{ox}} \right)^2 \quad (1.32)$$

$$b_b = \left( 1 + \frac{C_{box}}{C_{ox}} + \frac{C_{box}}{C_{soi}} + a_b \cdot \frac{2 \cdot V_b}{V_{ox}} \right) \quad (1.33)$$

$$c_b = \frac{2 \cdot C_{ox}}{C_{soi}} + \left( \frac{C_{ox}}{C_{soi}} \right)^2 + \left( \frac{C_{box}}{C_{ox}} + \frac{C_{box}}{C_{soi}} \right) \cdot \frac{V_b}{V_{ox}} + \left( \frac{C_{box}}{2 \cdot C_{ox}} \cdot \frac{V_b}{V_{ox}} \right)^2 + \frac{V_g}{V_{ox}} \quad (1.34)$$

$$V_p = V_{ox} \cdot \frac{2 \cdot c_b}{b_b + \sqrt{b_b^2 - 4 \cdot a_b \cdot c_b}} \quad (1.35)$$

- $V_g - V_b \geq -V_{b_{sw}}$  &  $V_g - V_b \leq V_{g_{sw}}$ :

$$V_{bb} = V_b - V_{box} \quad (1.36)$$

$$V_{gg} = V_g - V_{ox} \quad (1.37)$$

$$V_p = \frac{(V_{gg} - V_{bb})^2 + 2 \cdot V_m \cdot (V_{gg} + V_{bb}) + V_m^2}{4 \cdot V_m} \quad (1.38)$$

- Source and drain voltage including pinch-off and velocity saturation

$$\text{if } VP > 0 \ \& \ V_p \leq 0: V_{sp} = \frac{1}{2} \cdot \left\{ V_{s1} + V_p - \sqrt{(V_{s1} - V_p)^2 + \delta_v} \right\} \quad (1.39)$$

$$\text{if } VP > 0 \ \& \ V_p > 0: V_{sp} = \frac{1}{2} \cdot \left\{ \frac{4 \cdot V_{s1} \cdot V_p - \delta_v}{V_{s1} + V_p + \sqrt{(V_{s1} - V_p)^2 + \delta_v}} \right\} \quad (1.40)$$

$$VP \leq 0: V_{sp} = V_{s1} \quad (1.41)$$

$$VP > 0: V_c = VSAT_T + V_p - V_{sp} - \sqrt{VSAT_T^2 + (V_p - V_{sp})^2} \quad (1.42)$$

$$VP \leq 0: V_c = VSAT_T \quad (1.43)$$

$$V_{dp} = V_{sp} + \frac{(V_{d1} - V_{s1}) \cdot V_c}{PSAT \sqrt{(V_{d1} - V_{s1})^{PSAT} + V_c^{PSAT}}} \quad (1.44)$$

- Integration boundary voltages

$$\begin{array}{lll} V_{sp} < V_b: & V_{dp} < V_b: & V_{ab} = V_{dp} \\ & V_{dp} \geq V_b: & V_{ab} = V_b \end{array}$$

$$V_{sp} \geq V_b: \quad V_{ab} = V_{sp}$$

$$\begin{array}{lll} V_{sp} < V_g: & V_{dp} < V_g: & V_{ag} = V_{dp} \\ & V_{dp} \geq V_g: & V_{ag} = V_g \end{array}$$

$$V_{sp} \geq V_g: \quad V_{ag} = V_{sp}$$

- Current increase due to accumulation at the handle wafer

$$V_{sp} < V_b: \quad I_{b1} = \frac{1}{2} \{ (V_b - V_{sp})^2 - (V_b - V_{ab})^2 \} \cdot \frac{C_{box}}{Q_{soi} \cdot RON_T} \quad (1.45)$$

$$V_{sp} \geq V_b: \quad I_{b1} = 0$$

- Current reduction due to depletion at the handle wafer

$$V_{dp} \geq V_b: \quad Y_{dpb} = \frac{(V_{dp} - V_b)/V_{box}}{1 + \sqrt{1 + (V_{dp} - V_b)/V_{box}}} \quad (1.46)$$

$$Y_{abb} = \frac{(V_{ab} - V_b)/V_{box}}{1 + \sqrt{1 + (V_{ab} - V_b)/V_{box}}} \quad (1.47)$$

$$I_{b2} = \frac{-2 \cdot k_b \cdot V_{box}^{3/2}}{Q_{soi} \cdot RON_T} \cdot \left( \frac{Y_{dpb}^2 - Y_{abb}^2}{2} + \frac{Y_{dpb}^3 - Y_{abb}^3}{3} \right) \quad (1.48)$$

$$V_{dp} < V_b: \quad I_{b2} = 0$$

- Current increase due to accumulation at the gate

$$V_{sp} < V_g: \quad I_{g1} = \frac{1}{2} \{ (V_g - V_{sp})^2 - (V_g - V_{ag})^2 \} \cdot \frac{C_{box}}{Q_{soi} \cdot RON_T} \quad (1.49)$$

$$V_{sp} \geq V_g: \quad I_{g1} = 0$$

- Current reduction due to depletion at the gate

$$V_{dp} \geq V_g: \quad Y_{dpg} = \frac{(V_{dp} - V_g)/V_{ox}}{1 + \sqrt{1 + (V_{dp} - V_g)/V_{ox}}} \quad (1.50)$$

$$Y_{agg} = \frac{(V_{ag} - V_g)/V_{ox}}{1 + \sqrt{1 + (V_{ag} - V_g)/V_{ox}}} \quad (1.51)$$

$$I_{g2} = \frac{-2 \cdot k_g \cdot V_{ox}^{3/2}}{Q_{soi} \cdot RON_T} \cdot \left( \frac{Y_{dpg}^2 - Y_{agg}^2}{2} + \frac{Y_{dpg}^3 - Y_{agg}^3}{3} \right) \quad (1.52)$$

$$V_{dp} < V_g: \quad I_{g2} = 0$$

- Total ohmic current

$$VP > 0: \quad I_{ohm} = \frac{V_{dp} - V_{sp}}{RON_T} + I_{b1} + I_{b2} + I_{g1} + I_{g2} \quad (1.53)$$

$$VP \leq 0: \quad I_{ohm} = \frac{V_{dp} - V_{sp}}{RON_T} \quad (1.54)$$

- Total current including velocity saturation

$$I_{ds} = sign \cdot I_{ohm} \cdot \left( 1 + \frac{V_{d1} - V_{dp}}{VR_{sat}} \right) \quad (1.55)$$

### 1.3.5 Substrate charge model

If  $TBOX \leq 0$  then  $V_{b_1} = V_{b_2} = V_{b_3} = V_{b_4} = V_{b_5} = V_{b_6} = V_{b_7} = 0$

- $V_{b_1}$ : accumulation part  $q_b$   
 $V_{b_2}$ : depletion part  $q_b$   
 $V_{b_3}$ : accumulation part  $q_b^2$   
 $V_{b_4}$ : depletion part  $q_b^2$   
 $V_{b_5}$ : accumulation part  $q_b$  times accumulation part  $q_g$   
 $V_{b_6}$ : depletion part  $q_b$  times accumulation part  $q_g$   
 $V_{b_7}$ : depletion part  $q_b$  times depletion part  $q_g$

$$F_c = \frac{(V_p - V_{sp})^4}{(V_p - V_{sp})^4 + (VP/100)^4} \cdot \frac{V_{dp} - V_{sp}}{V_0 + V_{dp} - V_{sp}} \quad (1.56)$$

$$V_{sp} < V_b: V_{b_1} = \frac{1}{I_{ohm} \cdot RON_T} \cdot \frac{1}{2} \{ (V_b - V_{sp})^2 - (V_b - V_{ab})^2 \} \quad (1.57)$$

$$V_{b_3} = \frac{-C_{box}}{3 \cdot Q_{soi} \cdot I_{ohm} \cdot RON_T} \cdot \{ (V_b - V_{ab})^3 - (V_b - V_{sp})^3 \} \quad (1.58)$$

$$V_{sp} \geq V_b: V_{b_1} = 0; \quad V_{b_3} = 0$$

$$V_{dp} \geq V_b: V_{b_2} = \frac{-2 \cdot k_b \cdot T_{box} \cdot V_{box}^{3/2}}{\epsilon_{ox} \cdot I_{ohm} \cdot RON_T} \cdot \left( \frac{Y_{dpb}^2 - Y_{abb}^2}{2} + \frac{Y_{dpb}^3 - Y_{abb}^3}{3} \right) \quad (1.59)$$

$$V_{b_4} = \frac{2 \cdot k_b^2 \cdot T_{box} \cdot V_{box}^2}{Q_{soi} \cdot \epsilon_{ox} \cdot I_{ohm} \cdot RON_T} \cdot \left( \frac{Y_{dpb}^3 - Y_{abb}^3}{3} + \frac{Y_{dpb}^4 - Y_{abb}^4}{4} \right) \quad (1.60)$$

$$V_{dp} < V_b: \quad V_{b_2} = 0$$

$$V_{b_4} = 0$$

$$V_g \& V_b > V_{sp}: \quad V_g < V_b: \quad V_{a_i} = V_{ag}$$

$$V_g \geq V_b: \quad V_{a_i} = V_{ab}$$

$$V_{b_5} = \frac{-C_{ox}}{Q_{soi} \cdot I_{ohm} \cdot RON_T} \cdot \left\{ \begin{array}{l} (V_g - V_b) \cdot \frac{(V_b - V_{a_i})^2 - (V_b - V_{sp})^2}{2} + \\ \frac{(V_b - V_{a_i})^3 - (V_b - V_{sp})^3}{3} \end{array} \right\} \quad (1.61)$$

$$V_g \text{ or } V_b \leq V_{sp}: \quad V_{b_5} = 0$$

$$V_{dp} \geq V_b \& V_{sp} < V_g \& V_b < V_g:$$

$$Y_{agb} = \frac{(V_{ag} - V_b)/V_{box}}{1 + \sqrt{1 + (V_{ag} - V_b)/V_{box}}} \quad (1.62)$$

$$V_{b_6} = \frac{-2 \cdot k_b \cdot C_{ox} \cdot T_{box} \cdot V_{box}^{5/2}}{Q_{soi} \cdot \epsilon_{ox} \cdot I_{ohm} \cdot RON_T} \cdot \left\{ \frac{V_g - V_b}{V_{box}} \cdot \left( \frac{Y_{agb}^2 - Y_{abb}^2}{2} + \frac{Y_{agb}^3 - Y_{abb}^3}{3} \right) - \right.$$

$$\left. \left( 2 \cdot \frac{Y_{agb}^3 - Y_{abb}^3}{3} + 3 \cdot \frac{Y_{agb}^4 - Y_{abb}^4}{4} + \frac{Y_{agb}^5 - Y_{abb}^5}{5} \right) \right\} \quad (1.63)$$

$$V_{dp} \geq V_g \& V_{sp} < V_b \& V_g < V_b:$$

$$Y_{abg} = \frac{(V_{ab} - V_g)/V_{ox}}{1 + \sqrt{1 + (V_{ab} - V_g)/V_{ox}}} \quad (1.64)$$

$$V_{b_6} = \frac{2 \cdot k_g \cdot V_{ox}^{5/2}}{Q_{soi} \cdot I_{ohm} \cdot RON_T} \cdot \left\{ \frac{V_b - V_g}{V_{ox}} \cdot \left( \frac{Y_{agg}^2 - Y_{abg}^2}{2} + \frac{Y_{agg}^3 - Y_{abg}^3}{3} \right) - \left( 2 \cdot \frac{Y_{agg}^3 - Y_{abg}^3}{3} + 3 \cdot \frac{Y_{agg}^4 - Y_{abg}^4}{4} + \frac{Y_{agg}^5 - Y_{abg}^5}{5} \right) \right\} \quad (1.65)$$

$$V_g \& V_b < V_{sp} \text{ or } V_g \& V_b > V_{dp}: V_{b_6} = 0$$

$$V_g \& V_b < V_{dp}: \quad \begin{array}{ll} V_g > V_b & V_{ad} = V_{ag} \\ V_g \leq V_b & V_{ad} = V_{ab} \end{array}$$

$$Y_{adb} = \frac{(V_{ad} - V_b)/V_{box}}{1 + \sqrt{1 + (V_{ad} - V_b)/V_{box}}} \quad (1.66)$$

$$Y_{adg} = \frac{(V_{ad} - V_g)/V_{ox}}{1 + \sqrt{1 + (V_{ad} - V_g)/V_{ox}}} \quad (1.67)$$

$$Z_0 = \frac{V_g - V_b - V_{ox} + V_{box}}{2} \quad (1.68)$$

$$\begin{aligned}
& \frac{k_g \cdot k_b \cdot T_{box}}{Q_{soi} \cdot RON_T \cdot C_{box} \cdot I_{ohm}} \cdot \\
Vb_7^{exact} = & \left[ \frac{1}{4} \cdot \sqrt{V_{box} \cdot V_{ox}} \cdot \left\{ \begin{aligned} & (V_{ox} - V_{box}) \cdot [(Y_{dpb} - Y_{dpg}) - (Y_{adb} - Y_{adg})] \\ & + V_{box} \cdot Y_{dpb} \cdot [Y_{dpb} \cdot (1 + Y_{dpb}) + Y_{dpg} \cdot (3 + 3 \cdot Y_{dpb} + Y_{dpb}^2)] \\ & - V_{box} \cdot Y_{adb} \cdot [Y_{adb} \cdot (1 + Y_{adb}) + Y_{adg} \cdot (3 + 3 \cdot Y_{adb} + Y_{adb}^2)] \\ & + V_{ox} \cdot Y_{dpg} \cdot [Y_{dpg} \cdot (1 + Y_{dpg}) + Y_{dpb} \cdot (3 + 3 \cdot Y_{dpg} + Y_{dpg}^2)] \\ & - V_{ox} \cdot Y_{adg} \cdot [Y_{adg} \cdot (1 + Y_{adg}) + Y_{adb} \cdot (3 + 3 \cdot Y_{adg} + Y_{adg}^2)] \end{aligned} \right\} \right. \\
& - z_0 \cdot \ln \frac{\sqrt{V_{box}} \cdot (1 + Y_{dpb}) + \sqrt{V_{ox}} \cdot (1 + Y_{dpg})}{\sqrt{V_{box}} \cdot (1 + Y_{adb}) + \sqrt{V_{ox}} \cdot (1 + Y_{adg})} \\
& - 2 \cdot V_{box}^{3/2} \cdot \sqrt{V_{ox}} \cdot \left( \frac{Y_{dpb}^2 - Y_{adb}^2}{2} + \frac{Y_{dpb}^3 - Y_{adb}^3}{3} \right) \\
& \left. - 2 \cdot V_{ox}^{3/2} \cdot \sqrt{V_{box}} \cdot \left( \frac{Y_{dpg}^2 - Y_{adg}^2}{2} + \frac{Y_{dpg}^3 - Y_{adg}^3}{3} \right) \right]
\end{aligned} \tag{1.69}$$

$$\begin{aligned}
& \frac{k_g \cdot k_b \cdot T_{box}}{\epsilon_{ox} \cdot Q_{soi} \cdot RON_T \cdot I_{ohm}} \cdot \\
Vb_7^{appro} = & \left[ \frac{1}{4 \cdot \sqrt{V_{box} \cdot V_{ox}}} \cdot \left\{ (V_{dp} - V_{ad}) \cdot [V_b \cdot V_g] - \frac{V_{dp}^2 - V_{ad}^2}{2} \cdot [V_g + V_b] + \frac{V_{dp}^3 - V_{ad}^3}{3} \right\} + \right. \\
& \left. \frac{1}{16 \cdot (V_{box} \cdot V_{ox})^{3/2}} \cdot \left\{ \begin{aligned} & (V_{dp} - V_{ad}) \cdot [V_b \cdot V_g \cdot (V_g \cdot V_{box} + V_b \cdot V_{ox})] - \\ & \frac{V_{dp}^2 - V_{ad}^2}{2} \cdot [V_g^2 \cdot V_{box} + V_b^2 \cdot V_{ox} + 2 \cdot V_b \cdot V_g \cdot (V_{box} + V_{ox})] + \\ & \frac{V_{dp}^3 - V_{ad}^3}{3} \cdot [V_g \cdot (2 \cdot V_{box} + V_{ox}) + V_b \cdot (V_{box} + 2 \cdot V_{ox})] - \\ & \frac{V_{dp}^4 - V_{ad}^4}{4} \cdot [V_{box} + V_{ox}] \end{aligned} \right\} \right]
\end{aligned} \tag{1.70}$$

$$Y_{sw} = \frac{V_{box} \cdot (Y_{dpb}^2 + Y_{adb}^2) + V_{ox} \cdot (Y_{dpg}^2 + Y_{adg}^2)}{V_0^2 \cdot (V_{box} + V_{ox})} \quad (1.71)$$

$$Sw = \frac{(1 + 2 \cdot V_o) \cdot Y_{sw}^2}{1 + Y_{sw}^2} - V_o \quad (1.72)$$

$$Sw > 1 : \quad V_{b_7} = Vb_7^{exact} \quad (1.73)$$

$$Sw < 0 : \quad V_{b_7} = Vb_7^{appr} \quad (1.74)$$

$$Sw \geq 0 \& Sw \leq 1 : \quad Vb_7 = Sw \cdot Vb_7^{exact} + (1 - Sw) \cdot Vb_7^{appr} \quad (1.75)$$

$$V_g \text{ or } V_b \geq V_{dp} : \quad Vb_7 = 0$$

$$Q_{b_x} = CBOX \cdot (V_{b_1} + V_{b_2} + V_{b_3} + V_{b_4} + V_{b_5} + V_{b_6} + V_{b_7}) \quad (1.76)$$

$$TBOX \leq 0 : \quad Q_{b_y} = 0$$

$$TBOX > 0$$

$$\bullet V_b \geq \left( \frac{V_{sp} + V_{dp}}{2} \right) : \quad Q_{b_y} = CBOX \cdot \left( V_b - \left( \frac{V_{sp} + V_{dp}}{2} \right) \right) \quad (1.77)$$

$$\bullet V_b < \left( \frac{V_{sp} + V_{dp}}{2} \right) : \quad Q_{b_y} = \frac{-CBOX \cdot k_b \cdot \frac{V_{sp} + V_{dp}}{2} - V_b}{C_{box} \cdot \sqrt{\frac{V_{sp} + V_{dp}}{2} - V_b + V_{box} + \sqrt{V_{box}}}} \quad (1.78)$$

$$Cb_{fix} = 0.01 \cdot CBOX + MULT \cdot 10^{-17} \quad (1.79)$$

$$Q_b = 0.99 \cdot Q_{b_z} + Cb_{fix} \cdot \{V_b - (V_d + V_s)/2\} \quad (1.80)$$

$$\text{If } F_c \leq 0 \text{ or } (V_{dp} - V_{sp}) \leq 1.0e - 4 \text{ then } Q_{b_z} = Q_{b_y} \quad (1.81)$$

$$\text{else if } F_c \geq 1 \text{ then } Q_{b_z} = Q_{b_x} \quad (1.82)$$

$$\text{else if } F_c < 1 \text{ then } Q_{b_z} = Q_{b_y} + F_c(Q_{b_x} - Q_{b_y}) \quad (1.83)$$

$$Qb_s = 0.5 \cdot Qb \quad (1.84)$$

$$Qb_d = 0.5 \cdot Qb \quad (1.85)$$

### 1.3.6 gate charge model

$$\text{If } TOX \leq 0 \text{ then } V_{g_1} = V_{g_2} = V_{g_3} = V_{g_4} = V_{g_5} = V_{g_6} = V_{g_7} = 0$$

$$\text{If } (V_{dp} - V_{sp}) > 1.0e - 4 \text{ and } F_c > 0:$$

$$V_{sp} < V_g: \quad V_{g_1} = \frac{(V_g - V_{sp})^2 - (V_g - V_{ag})^2}{2 \cdot I_{ohm} \cdot RON_T} \quad (1.86)$$

$$V_{g_3} = \frac{C_{ox}}{Q_{soi} \cdot I_{ohm} \cdot RON_T} \cdot \frac{(V_g - V_{sp})^3 - (V_g - V_{ag})^3}{3} \quad (1.87)$$

$$: \quad V_{g_1} = 0$$

$$(V_{sp} \geq V_g)m$$

$$V_{g_3} = 0$$

$$V_{dp} \geq V_g: \quad V_{g_2} = \frac{-2 \cdot k_g \cdot T_{ox} \cdot V_{ox}^{3/2}}{\epsilon_{ox} \cdot I_{ohm} \cdot RON_T} \cdot \left( \frac{Y_{dpg}^2 - Y_{agg}^2}{2} + \frac{Y_{dpg}^3 - Y_{agg}^3}{3} \right) \quad (1.88)$$

$$V_{g_4} = \frac{V_{ox}^2 \cdot 2 \cdot k_g^2 \cdot T_{ox}}{Q_{soi} \cdot \epsilon_{ox} \cdot I_{ohm} \cdot RON_T} \cdot \left( \frac{Y_{dpg}^3 - Y_{agg}^3}{3} + \frac{Y_{dpg}^4 - Y_{agg}^4}{4} \right) \quad (1.89)$$

$$V_{dp} < V_g: \quad V_{g_2} = 0$$

$$V_{g_4} = 0$$

If ( $C_{box} > 0$  and  $C_{ox} > 0$ )

$$V_{g_5} = \frac{C_{box}}{C_{ox}} (V_{b_5} + V_{b_6} + V_{b_7})$$

$$\text{otherwise} \quad V_{g_5} = 0 \quad (1.90)$$

$$Q_{g_x} = CGATE \cdot (V_{g_1} + V_{g_2} + V_{g_3} + V_{g_4} + V_{g_5}) \quad (1.91)$$

$$TOX \leq 0: \quad Q_{gy} = 0$$

$TOX > 0$ :

$$\bullet V_g \geq \left( \frac{V_{sp} + V_{dp}}{2} \right): Q_{g_y} = -CGATE \cdot \left( \frac{V_{sp} + V_{dp}}{2} - V_g \right) \quad (1.92)$$

$$\bullet V_g < \left( \frac{V_{sp} + V_{dp}}{2} \right): Q_{g_y} = \frac{-CGATE \cdot k_g \cdot \frac{V_{sp} + V_{dp}}{2} - V_g}{C_{ox} \cdot \sqrt{\frac{V_{sp} + V_{dp}}{2} - V_g + V_{ox} + \sqrt{V_{ox}}}} \quad (1.93)$$

$$Cg_{fix} = 0.01 \cdot CGATE + MULT \cdot 10^{-17} \quad (1.94)$$

$$Q_g = 0.99 \cdot Q_{g_z} + Cg_{fix} \cdot \{V_g - (V_d + V_s)/2\} \quad (1.95)$$

$$\text{If } F_c \leq 0 \text{ or } (V_{dp} - V_{sp}) \leq 1.0e - 4 \text{ then } Q_{g_z} = Q_{g_y} \quad (1.96)$$

$$\text{else if } F_c \geq 1 \text{ then } Q_{g_z} = Q_{g_x} \quad (1.97)$$

$$\text{else if } F_c < 1 \text{ then } Q_{g_z} = Q_{g_y} + F_c(Q_{g_x} - Q_{g_y}) \quad (1.98)$$

$$Qg_s = 0.5 \cdot Qg \quad (1.99)$$

$$(1.100)$$

$$(Qg_d = 0.5 \cdot Qg)m$$

### 1.3.7 Space charge in the channel

- Critical current for hot-carriers

$VP > 0$ :

$$V_g \geq V_{sp}: \quad Q_{gs} = C_{ox} \cdot (V_g - V_{sp}) \quad (1.101)$$

$$V_g < V_{sp}: \quad Q_{gs} = -k_g \cdot \frac{V_{sp} - V_g}{\sqrt{V_{sp} - V_g + V_{ox}} + \sqrt{V_{ox}}} \quad (1.102)$$

$$V_b \geq V_{sp}: \quad Q_{bs} = C_{box} \cdot (V_b - V_{sp}) \quad (1.103)$$

$$V_b < V_{sp}: \quad Q_{bs} = -k_b \cdot \frac{V_{sp} - V_b}{\sqrt{V_{sp} - V_b + V_{box}} + \sqrt{V_{box}}} \quad (1.104)$$

$$Q_{spx} = 1 + (Q_{gs} + Q_{bs})/Q_{soi} \quad (1.105)$$

$$I_{hc} = \frac{VSAT_T}{RON_T} \cdot \frac{Q_{spx} + \sqrt{Q_{spx}^2 + \delta_q}}{2} \quad (1.106)$$

$VP \leq 0$ :

$$I_{hc} = VSAT_T/RON_T \quad (1.107)$$

$$Q_{ds} = \text{sign} \cdot TAUSC \cdot I_{hc} \left[ \left\{ 1 + \left( \frac{|I_{ds}|}{I_{hc}} \right)^{2 \cdot PSAT} \right\}^{1/(2 \cdot PSAT)} - 1 \right] \quad (1.108)$$

$$Q_d = -\frac{1}{2}(Q_b + Q_g) + Q_{ds} \quad (1.109)$$

$$Q_s = -\frac{1}{2}(Q_b + Q_g) - Q_{ds} \quad (1.110)$$

## Numerical Adaptations

To implement SOI FET Model, level 40 in a circuit simulator, care must be taken of the numerical stability of the simulation program. The functions as well as their derivatives should be continuous at any bias condition that may occur during the iteration cycle.

## Numerical Problems and Solutions

$F_c$  must be set to zero when  $I_{ohm}$  gets close to zero or even negative. This prevents divisions by zero in the substrate charge model.

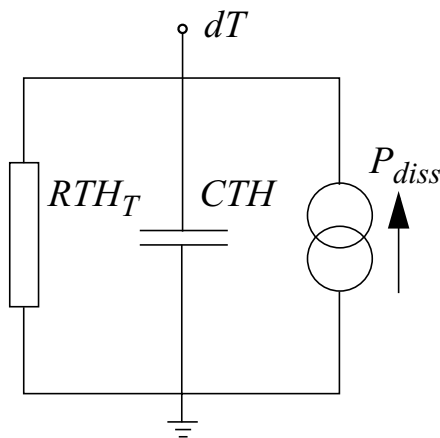
### 1.3.8 Numerical Adaptation

To implement the model in a circuit simulator, care must be taken of the numerical stability of the simulation program. A non-existent conductance,  $G_{min}$ , is connected between the nodes  $DS$ . The value of the conductance is  $10^{-15}$  [1/ $\Omega$ ].

## 1.4 Self-heating

### 1.4.1 Equivalent circuit

Self-heating is part of the model. It is defined in the usual way by adding a self-heating network (see figure 2) containing a current source describing the dissipated power and both a thermal resistance  $R_{TH}$  and a thermal capacitance  $C_{TH}$ .



Material	ATH
Si	1.3
Ge	1.25
GaAs	1.25
AlAs	1.37
InAs	1.1
InP	1.4
GaP	1.4
SiO <sub>2</sub>	0.7

Figure 2: On the left, the self-heating network, where the node voltage  $V_{dT}$  is used in the temperature scaling relations. Note that for increased flexibility the node  $dT$  is available to the user. On the right are parameter values that can be used for  $A_{th}$ .

The resistance and capacitance are both connected between ground and the temperature node  $d_T$ . The value of the voltage  $V_{dT}$  at the temperature node gives the increase in local temperature, which is included in the calculation of the temperature scaling relation (1.1), see section 1.3.2 on page 8.

For the value of  $A_{th}$  we recommend using values from literature that describe the temperature scaling of the thermal conductivity. For the most important materials, the values are given in figure 2, which is largely based on Ref. [ 1], see also [ 2].

For example, if the value of  $V_{dT}$  is 0.5V, the increase in temperature is 0.5 degrees Celsius.

## 1.4.2 Model equations

The total dissipated power is a sum of the dissipated power of each branch of the equivalent circuit and is given by:

$$P_{diss} = I_{DS} \cdot V_{DS}$$

The total dissipation applies for the geometrical model (mnt<sup>1</sup>, mpt<sup>2</sup>, mos40t<sup>3</sup>).

## 1.4.3 Usage

Below a *Pstar* example is given to illustrate how self-heating works.

### q Example

Title: example self-heating 40;

```

circuit;
mnt_1(Vd, Vg, Vs, 0, dt) level=40, Rth=1e6,Cth=1e-9;
R_1 ( Vdd, Vd) 100;
R_2 ( Vgg, Vg) 1k;
R_3 ( Vs, 0) 100;
e_SRC_2 (Vgg ,net101) 5;
e_SRC_1 ( Vdd, 0) 1;
e_SRC_3 ( net101, 0) 0;
end;

dc;
print: vn(dt), op(pdiss.mnt_1);
end; run;

result:
DC Analysis.
VN(DT) = 24.764E+00
Pdiss.MNT_1 = 24.764E-06

```

The voltage on node *dT* is 24.764e+0 V, which means that the local temperature is increased by 24.764e+0 °C.

---

1.*Pstar* model name.

2.*Pstar* model name.

3.*Spectre/ADS* model name.

## 1.5 DC operating point output

The DC operating point output facility gives information on the state of a device at its operation point. Besides terminal currents and voltages, the magnitudes of linearized internal elements are given. In some cases meaningful quantities can be derived which are then also given (e.g. u). The objective of the DCOP-facility is twofold:

- Calculate small-signal equivalent circuit element values.
- Open a window on the internal bias conditions of the device and its basic capabilities (e.g. u).

Below the printed items are described.  $C_{x(y)}$  indicates the derivate of the charge  $Q$  at terminal  $x$  to the voltage at terminal  $y$ , when all other terminals remain constant.

Quantity	Equation	Description
Level	40	Model level
$I_{ds}$	$I_{ds}$	Drain Source current
$V_{ds}$		Drain Source voltage
$V_{gs}$		Gate Source voltage
$V_{bs}$		Bulk Source voltage
$V_p$	$V_p$	Channel pinch-off voltage
$g_m$	$dI_{ds}/dV_g$	Transconductance
$g_{mb}$	$dI_{ds}/dV_b$	Bulk transconductance
$g_{ds}$	$dI_{ds}/dV_d$	Output conductance
$Q_g$		Gate charge
$C_{gd}$	$-dQ_g/dV_d$	Gate charge dependence on drain voltage
$C_{gg}$	$dQ_g/dV_g$	Gate charge dependence on gate voltage
$C_{gs}$	$-dQ_g/dV_s$	Gate charge dependence on source voltage
$C_{gb}$	$-dQ_g/dV_b$	Gate charge dependence on bulk voltage
$Q_b$		Bulk charge

$C_{bd}$	$-dQ_b/dV_d$	Bulk charge dependence on drain voltage
$C_{bg}$	$-dQ_b/dV_g$	Bulk charge dependence on gate voltage
$C_{bs}$	$-dQ_b/dV_s$	Bulk charge dependence on source voltage
$C_{bb}$	$+dQ_b/dV_b$	Bulk charge dependence on bulk voltage
$Q_d$		Drain charge
$C_{dd}$	$+dQ_d/dV_d$	Drain charge dependence on drain voltage
$C_{dg}$	$-dQ_d/dV_g$	Drain charge dependence on gate voltage
$C_{ds}$	$-dQ_d/dV_s$	Drain charge dependence on source voltage
$C_{db}$	$-dQ_d/dV_b$	Drain charge dependence on bulk voltage
$Q_s$		Source charge
$C_{sd}$	$-dQ_s/dV_d$	Source charge dependence on drain voltage
$C_{sg}$	$-dQ_s/dV_g$	Source charge dependence on gate voltage
$C_{ss}$	$+dQ_s/dV_s$	Source charge dependence on source voltage
$C_{sb}$	$-dQ_s/dV_b$	Source charge dependence on bulk voltage
$u$	$g_m/g_{ds}$	Transistor gain
$R_{out}$	$1/g_{ds}$	Small signal output resistance
$V_{early}$	$ I_{ds} /g_{ds}$	Equivalent Early voltage
$I_{ohm}$	$I_{ohm}$	Drain source current excluding velocity saturation
$I_{hc}$	$I_{hc}$	Critical current for velocity saturation

The additional operating point output for the model including self-heating (see section 1.4), is listed in the table below.

Quantity	Equation	Description
$T_k$	$T_k$	Actual temperature including self-heating
$P_{diss}$	$P_{diss}$	Power dissipation

When the parameter PRINTSCALED is set to 1, the device parameter set after geometrical and temperature scaling is added to the OP output:

Quantity	Description
<i>RONT</i>	Ohmic resistance at zero bias
<i>RSATT</i>	Space charge resistance at zero bias
<i>VSATT</i>	Critical drain-source voltage for hot carriers
<i>PSAT</i>	Velocity saturation coefficient
<i>VP</i>	Pinch off voltage at zero gate and substrate voltages
<i>TOX</i>	Gate oxide thickness
<i>DCH</i>	Doping level channel
<i>TBOX</i>	Box oxide thickness
<i>CGATE</i>	Gate capacitance at zero bias
<i>CBOX</i>	Wafer capacitance
<i>TAUSC</i>	Space charge transit time of the channel

### Remarks:

- When  $V_{ds} < 0$ ,  $g_m$  and  $g_{mb}$  are calculated with drain and source terminals interchanged (see section on Channel Type Declarations). The terminal voltages and  $I_{DS}$  keep their sign..
- The signs of  $V_p$  follow the conventions of the model parameter set. The parameter set is always assumed to correspond to an n-channel device..
- *MULT* is a scaling parameter that multiplies all currents and charges by the value of *MULT*. This is equivalent to putting *MULT* (a number) MOS transistors in parallel. And as a consequence *MULT* effects the operating point output.
- A non-existent conductance,  $G_{min}$ , is connected between the nodes *DS*. This conductance  $G_{min}$  does not influence the DC-operating point.



## 1.6 Simulator specific items

### 1.6.1 Pstar syntax

n channel	:	mn_n (d,g,s,b)	level=40, <parameters>
p channel	:	mp_n (d,g,s,b)	level=40, <parameters>
n channel self-heating	:	mnt_n (d,g,s,b,dt)	level=40, <parameters>
p channel self-heating	:	mpt_n (d,g,s,b,dt)	level=40, <parameters>
n	:	occurrence indicator	
<parameters>	:	list of model parameters	

d,g,s,b and dt are drain, gate, source, bulk and self-heating terminals respectively.

### 1.6.2 Spectre syntax

n channel	:	model modelname mos40 type=n <modpar> componentname d g s b modelname <inpar>	
p channel	:	model modelname mos40 type=p <modpar> componentname d g s b modelname <inpar>	
n channel self-heating	:	model modelname mos40t type=n <modpar> componentname d g s b dt modelname <inpar>	
p channel self-heating	:	model modelname mos40t type=p <modpar> componentname d g s b dt modelname <inpar>	
modelname	:	name of model, user defined	
componentname	:	occurrence indicator	
<modpar>	:	list of model parameters	
<inpar>	:	list of instance parameters	

d,g,s,b and dt are drain, gate, source, bulk and self-heating terminals respectively.

## 3 Note

Warning! In Spectre, use only the parameter statements type=n or type=p. Using any other string and/or numbers will result in unpredictable and possibly erroneous results.

### 1.6.3 ADS syntax

n channel	:	model modelname mos40 gender=1 <modpar> modelname:componentname d g s b <instpar>
p channel	:	model modelname mos40 gender=0 <modpar> modelname:componentname d g s b <instpar>
n channel self-heating	:	model modelname mos40t gender=1 <modpar> modelname:componentname d g s b dt <instpar>
p channel self-heating	:	model modelname mos40t gender=0 <modpar> modelname:componentname d g s b dt <instpar>
modelname	:	name of model, user defined
componentname	:	occurrence indicator
<modpar>	:	list of model parameters
<instpar>	:	list of instance parameters

d,g,s,b and dt are drain, gate, source, bulk and self-heating terminals respectively.

### 1.6.4 The ON/OFF condition for Pstar

The solution for a circuit involves a process of successive calculations. The calculations are started from a set of 'initial guesses' for the electrical quantities of the nonlinear elements. A simplified DCAPPROX mechanism for devices using ON/OFF keywords is mentioned in [3]. By default the devices start in the default state.

n-channel			
	Default	ON	OFF
$V_{DS}$	2.0	2.0	2.0
$V_{GS}$	-2.0	-2.0	-4.0
$V_{SB}$	0.0	0.0	-2.0

p-channel			
	Default	ON	OFF
$V_{DS}$	-2.0	-2.0	-2.0
$V_{GS}$	2.0	2.0	4.0
$V_{SB}$	0.0	0.0	+2.0

### 1.6.5 The ON/OFF condition for Spectre

n-channel							
	OFF	Triode	Saturation	Subthreshold	Reverse	Forward	Breakdown
$V_{DS}$	0.0	0.75	1.25	0.0	0	0	0
$V_{GS}$	0.0	2.0	1.25	0.0	0	0	0
$V_{SB}$	0.0	0.0	0.0	0.0	0	0	0

p-channel							
	OFF	Triode	Saturation	Subthreshold	Reverse	Forward	Breakdown
$V_{DS}$	0.0	-0.75	-1.25	0.0	0	0	0
$V_{GS}$	0.0	-2.0	-1.25	0.0	0	0	0
$V_{SB}$	0.0	0.0	-1.25	0.0	0	0	0

### 1.6.6 The ON/OFF condition for ADS

n-channel	
	Default
$V_{DS}$	0
$V_{GS}$	0
$V_{SB}$	0

p-channel	
	Default
$V_{DS}$	0
$V_{GS}$	0
$V_{SB}$	0

## 1.7 References

- [1] V. Palankovski R. Schultheis and S. Selberherr, *Modelling of power hetero-junction bipolar transistor on gallium arsenide*, IEEE Trans. Elec. Dev., vol 48, pp. 1264-1269, 2001. Note: the paper uses  $\alpha = 1.65$  for Si, but  $\alpha = 1.3$  gives a better fit: also,  $k_{300}$  for GaAs is closer to 40 than to the published value of 46 (Palankovski, personal communication).
- [2] Sze, S.M., *Physics of semiconductor devices*, 2<sup>nd</sup> edition, John Wiley & Sons, Inc., New York, 1981
- [3] **Pstar** User Manual.



# **A Hyp functions**

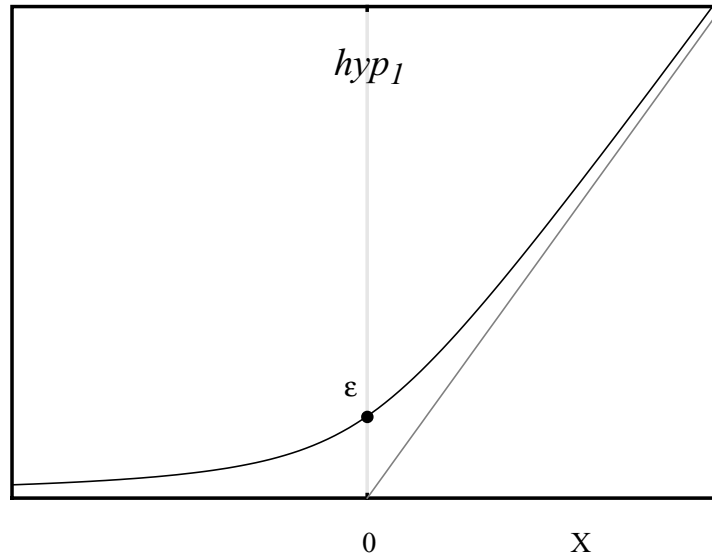


Figure 3:  $hyp_1(x;\epsilon) = \frac{1}{2} \cdot (x + \sqrt{x^2 + 4 \cdot \epsilon^2})$

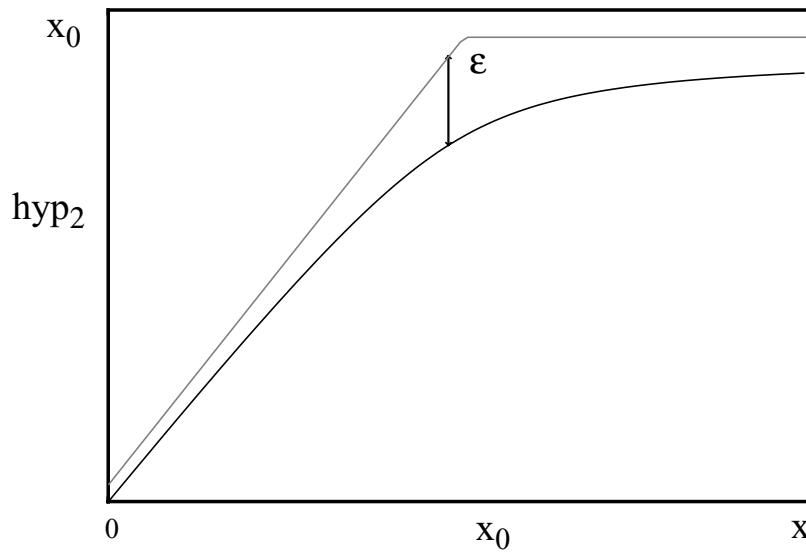


Figure 4:  $hyp_2(x;x_0;\epsilon) = x - hyp_1(x - x_0;\epsilon)$

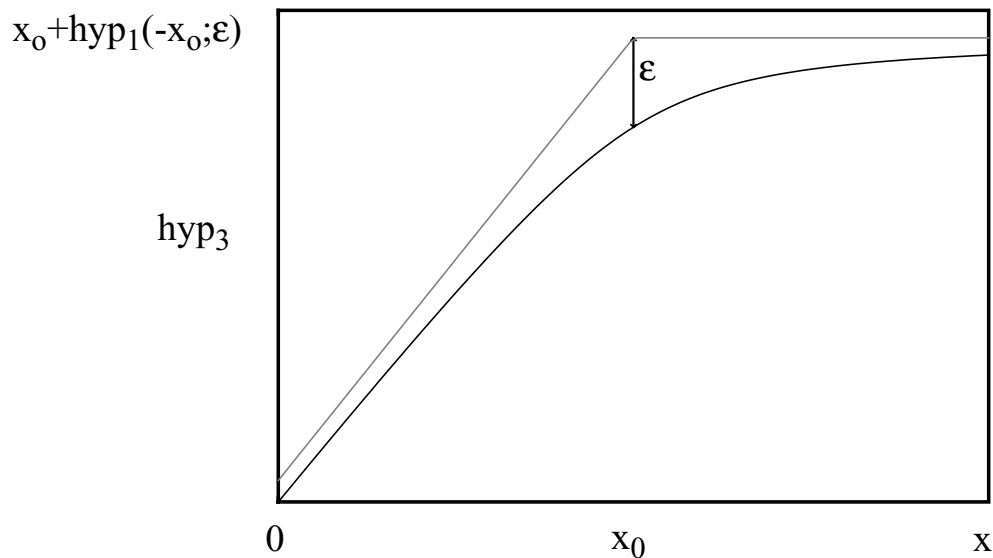


Figure 5:  $hyp_3(x; x_0; \epsilon) = hyp_2(x; x_0; \epsilon) - hyp_2(0; x_0; \epsilon)$  for  $\epsilon = \epsilon(x_0)$

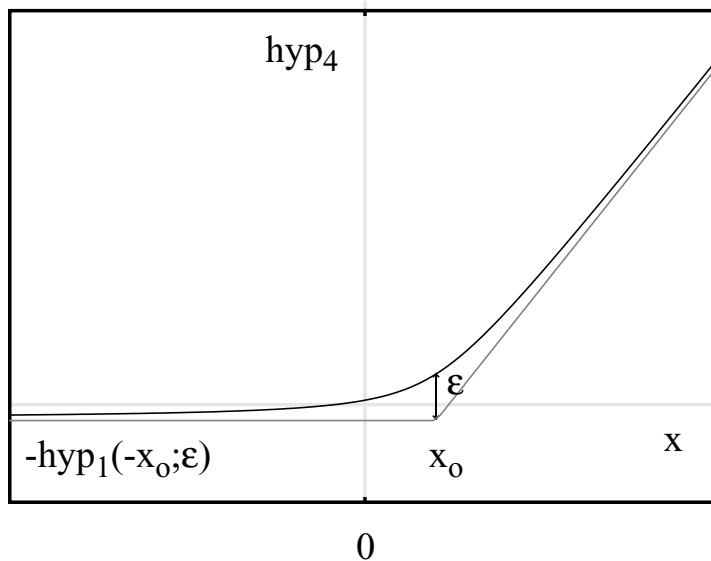


Figure 6:  $hyp_4(x; x_0; \epsilon) = hyp_1(x - x_0; \epsilon) - hyp_1(-x_0; \epsilon)$

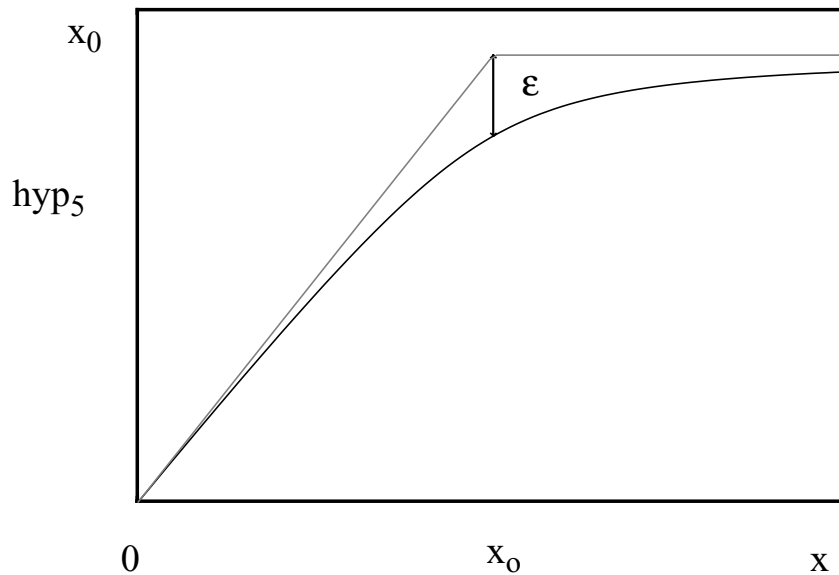


Figure 7:  $hyp_5(x; x_0; \varepsilon) = x_0 - hyp_1\left(x_0 - x - \frac{\varepsilon^2}{x_0}, \varepsilon\right)$  for  $\varepsilon = \varepsilon(x_0)$

**The hypm-function:**

$$hypm[x, y; m] = \frac{x \cdot y}{(x^{2 \cdot m} + y^{2 \cdot m})^{1/(2 \cdot m)}} \quad (1.111)$$

# **B** Spectre Specific Information

## Imax, Imelt, Jmelt parameters

### Introduction

Imax, Imelt and Jmelt are Spectre-specific parameters used to help convergence and to prevent numerical problems. We refer in this text only to the use of Imax model parameter in Spectre with SiMKit devices since the other two parameters, Imelt and Jmelt, are not part of the SiMKit code. For information on Imelt and Jmelt refer to Cadence documentation.

### Imax model parameter

Imax is a model parameter present in the following SiMKit models:

- juncap and juncap2
- psp and pspnqs (since they contain juncap models)

In Mextram 504 (bjt504) and Modella (bjt500) SiMKit models, Imax is an internal parameter and its value is set through the adapter via the Spectre-specific parameter Imax.

The default value of the Imax model parameter is 1000A. Imax should be set to a value which is large enough so it does not affect the extraction procedure.

In models that contain junctions, the junction current can be expressed as:

$$I = I_s \exp\left(\frac{V}{N \cdot \phi_{TD}} - 1\right) \quad (1.112)$$

The exponential formula is used until the junction current reaches a maximum (explosion) current Imax.

$$I_{max} = I_s \exp\left(\frac{V_{expl}}{N \cdot \phi_{TD}} - 1\right) \quad (1.113)$$

The corresponding voltage for which this happens is called Vexpl (explosion voltage). The voltage explosion expression can be derived from (1):

$$V_{expl} = N \cdot \phi_{TD} \log\left(\frac{I_{max}}{I_s}\right) + 1 \quad (1.114)$$

For  $V > V_{expl}$  the following linear expression is used for the junction current:

$$I = I_{max} + (V - V_{expl}) \frac{I_s}{N \cdot \phi_{TD}} \exp\left(\frac{V_{expl}}{N \cdot \phi_{TD}}\right) \quad (1.115)$$

## Region parameter

Region is an Spectre-specific model parameter used as a convergence aid and gives an estimated DC operating region. The possible values of region depend on the model:

- For Bipolar models:
  - subth: Cut-off or sub-threshold mode
  - fwd: Forward
  - rev: Reverse
  - sat: Saturation.
  - off<sup>1</sup>
  -
- For MOS models:
  - subth: Cut-off or sub-threshold mode;
  - triode: Triode or linear region;
  - sat: Saturation
  - off<sup>1</sup>

For PSP and PSPNQS all regions are allowed, as the PSP(NQS) models both have a MOS part and a juncap (diode). Not all regions are valid for each part, but when e.g. region=forward is set, the initial guesses for the MOS will be set to zero. The same holds for setting a region that is not valid for the JUNCAP.

- For diode models:
  - fwd: Forward
  - rev: Reverse
  - brk: Breakdown
  - off<sup>1</sup>

## Model parameters for device reference temperature in Spectre

This text describes the use of the tnom, tref and tr model parameters in Spectre with SiMKit devices to set the device reference temperature.

---

<sup>1</sup>.Off is not an electrical region, it just states that the user does not know in what state the device is operating

A Simkit device in Spectre has three model parameter aliases for the model reference temperature, `tnom`, `tref` and `tr`. These three parameters can only be used in a model definition, not as instance parameters.

There is no difference in setting `tnom`, `tref` or `tr`. All three parameters have exactly the same effect. The following three lines are therefore completely equivalent:

```
model nmos11020 mos11020 type=n tnom=30
model nmos11020 mos11020 type=n tref=30
model nmos11020 mos11020 type=n tr=30
```

All three lines set the reference temperature for the `mos11020` device to 30 C.

Specifying combinations of `tnom`, `tref` and `tr` in the model definition has no use, only the value of the last parameter in the model definition will be used. E.g.:

```
model nmos11020 mos11020 type=n tnom=30 tref=34
```

will result in the reference temperature for the `mos11020` device being set to 34 C, `tnom=30` will be overridden by `tref=34` which comes after it.

When there is no reference temperature set in the model definition (so no `tnom`, `tref` or `tr` is set), the reference temperature of the model will be set to the value of `tnom` in the options statement in the Spectre input file. So setting:

```
options1 options tnom=23 gmin=1e-15 reltol=1e-12 \
  vabstol=1e-12 iabstol=1e-16
model nmos11020 mos11020 type=n
```

will set the reference temperature of the `mos11020` device to 23 C.

When no `tnom` is specified in the options statement and no reference temperature is set in the model definition, the default reference temperature is set to 27 C.

So the lines:

```
options1 options gmin=1e-15 reltol=1e-12 vabstol=1e-12 \
  iabstol=1e-16
model nmos11020 mos11020 type=n
```

will set the reference temperature of the `mos11020` device to 27 C.

The default reference temperature set in the SiMKit device itself is in the Spectre simulator never used. It will always be overwritten by either the default "options tnom", an explicitly set option tnom or by a tnom, tref or tr parameter in the model definition.



# C OvervoltageSpecification

## Overvoltage warnings in SiMKit

### Introduction

Overvoltage flagging is signalling that a (terminal) voltage is outside a specified safe range. A warning will be given when the conditions for giving a warning are fulfilled.

Simple checks for overvoltage have been added to the following models: mos903, mos1100, mos1101, mos1102, mos2002, mos2003, mos3100, mos4000, psp102, psp103.

The checks are done on terminal voltages of the models.

There are many ways to define overvoltage. For a general overvoltage flagging solution Verilog-A should be used.

### Extra parameters for overvoltage flagging

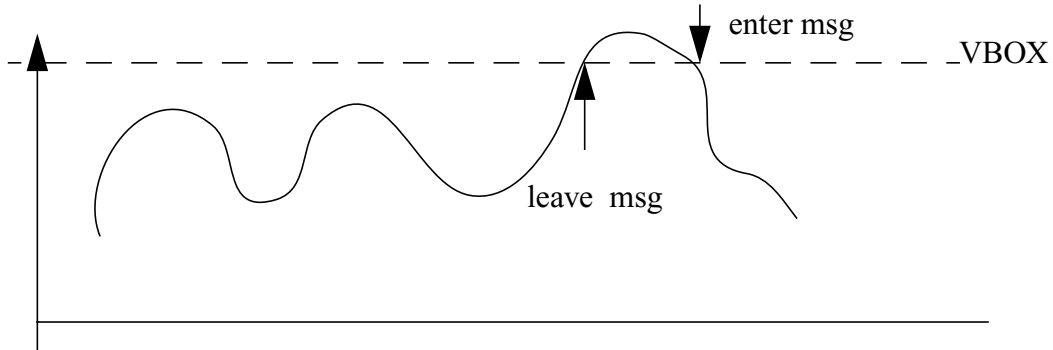
A set of extra parameters has been added to the mos models mos903, mos1100, mos1101, mos1102, mos2002, mos2003, mos3100, mos4000, psp102, psp103.

Table 1:

Name	Unit	Default	Description
VBOX	V	0.0	Oxide breakdown voltage. Checking will be done if $VBOX > 0$
VBDS	V	0.0	Drain-source breakdown voltage Checking will be done if $VBDS > 0$
TMIN	s	0.0	Ovcheck tmin value

For mos models the safe region is:

$$|V_{gs}| < VBOX \text{ and } |V_{gd}| < VBOX \text{ and } |V_{ds}| < VBDS$$



### Ovcheck: two terminal dummy model

A (dummy) two-terminal model ovcheck has been implemented that can be used to check if the voltage between the two terminals is within or without a so called safe region.

The model parameters are:

Name	Unit	Default	Description
VLOW	V	0.0	Lower bound of safe region
VHIGH	V	0.0	Upper bound of safe region Checking will be done when $VHIGH > VLOW$
TMIN	s	0.0	Ovcheck tmin value

For the ovcheck model the safe region is:

$$VLOW \leq V_{t1} - V_{t2} \leq VHIGH, \text{ where } t1 \text{ is the first and } t2 \text{ is the second terminal.}$$

### Functionality

#### In Spectre and Pstar

At the end of a DC analysis or in a transient analysis after each time step a check will be done if the device is inside or outside the safe region.

A warning is given whenever the device enters or leaves the safe region.

**In Spectre only**

To prevent too many warnings in a Spectre transient analysis the model parameter TMIN has been introduced. If the time between leaving and entering the safe region is less than the TMIN value no warning is given.

Because of the TMIN parameter a warning cannot be issued when leaving the safe region. A warning is given when the device enters the safe region again. This warning includes the time and the voltage when the safe region was exited. At the end of the transient warnings are given for devices that are still out of the safe range.

In Pstar TMIN may be specified as a model parameter, but it will be ignored.

# **D** Parameter PARAMCHK

## Parameter PARAMCHK

### Introduction

All models have the parameter PARAMCHK. It is not related to the model behavior, but has been introduced control the clip warning messages. Various situations may call for various levels of warnings. This is made possible by setting this parameter.

### PARAMCHK model parameter

This model parameter has been added to control the amount of clip warnings.

PARAMCHK	<	0	No clip warnings
PARAMCHK	≥	0	Clip warnings for instance parameters (default)
PARAMCHK	≥	1	Clip warnings for model parameters
PARAMCHK	≥	2	Clip warnings for electrical parameters at initialisation
PARAMCHK	≥	3	Clip warnings for electrical parameters during evaluation. This highest level is of interest only for selfheating jobs, where electrical parameters may change dependent on temperature.

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